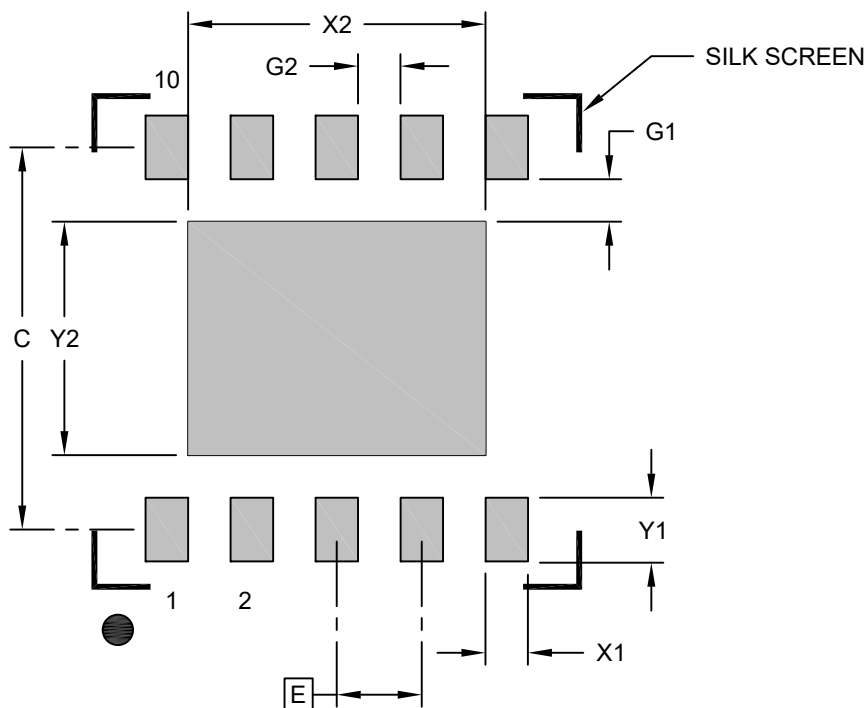


10-Lead Ultra Thin Plastic Dual Flat, No Lead Package (3VW) - 2x2x0.55 mm Body [UDFN] Saw Singulated with Pullback Leads

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Center Pad Width	X2			1.40
Center Pad Length	Y2			1.10
Contact Pad Spacing	C		1.80	
Contact Pad Width (X10)	X1			0.20
Contact Pad Length (X10)	Y1			0.30
Contact Pad to Center Pad (X10)	G1	0.20		
Contact Pad to Contact Pad (X8)	G2	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process